

Method for Bonding of Contact Surfaces

Abstract

This invention relates to method for bonding of a first, at least partially metallic contact surface of a first substrate to a second, at least partially metallic contact surface of a second substrate, with the following steps, especially the following progression:

- application of a sacrificial layer which is at least partially, especially predominantly soluble in the material of at least one of the contact surfaces to at least one of the contact surfaces,
- bonding of the contact surfaces with at least partial solution of the sacrificial layer in at least one of the contact surfaces.

Figure 1 in this respect.